

Negative Fixed Voltage Regulator

DESCRIPTION

The SG79xxA/SG79xx series of negative regulators offer self-contained, fixed-voltage capability with up to 1.5A of load current and input voltage up to -30V. With a variety of output voltages this regulator series is an optimum complement to the SG7800A/SG7800 positive three terminal regulators.

These units feature a unique band gap reference which allows the SG79xxA series to be specified with an output voltage tolerance of $\pm 1.5\%$.

The SG79xxA versions also offer much improved line regulation characteristics. All protective features of thermal shutdown, current limiting, and safe-area

control have been designed into these units and since these regulators require only a single output capacitor (SG79xx series) or a capacitor and 5mA minimum load (SG120 series) for satisfactory performance, ease of application is assured.

Although designed as fixed-voltage regulators, the output voltage can be increased through the use of a simple voltage divider. The low quiescent drain current of the device insures good regulation when this method is used.

These devices are available in hermetically sealed TO-257 (both case grounded 'G' and isolated 'IG'), TO-3, TO-39, and LCC packages.

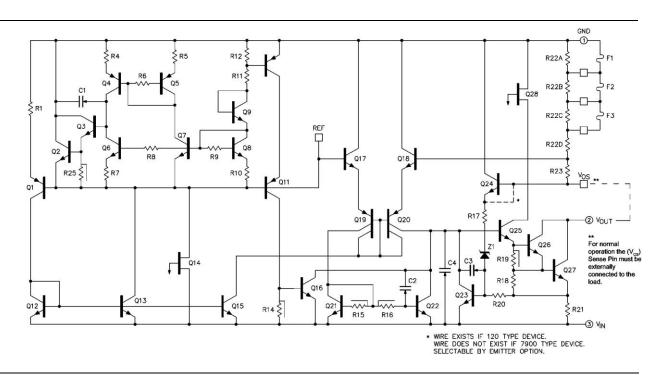
FEATURES

- Output Voltage Set Internally to ±1.5% on SG79xxA
- Output Current up to 1.5A
- Excellent Line and Load Regulation
- Foldback Current Limiting
- Thermal Overload Protection
- Voltages Available: -5V, -12V, -15V
- Contact Factory for Other Voltage Options
- Available in Surface Mount Package

HIGH RELIABILITY FEATURES

- Available to MIL-STD 883, ¶ 1.2.1
- MIL-M38510/11501BXA SG7905T-JAN
- MIL-M38510/11505BYA SG7905K-JAN
- MIL-M38510/11502BXA SG7912T-JAN
- MIL-M38510/11506BYA SG7912K-JAN
- MIL-M38510/11503BXA SG7915T-JAN
- MIL-M38510/11507BYA SG7915K-JAN
- MIL-M38510/11508BYA SG7924K-JAN
- MSC-AMS level "S" Processing Available
- Available to DSCC Standard Microcircuit Drawing (SMD)

SCHEMATIC DIAGRAM





ABSOLUTE MAXIMUM RATINGS

Parameter	Value	Units
Device Output Voltage	-5, -12, -15	V
Input Voltage	-35, -40 (V _{OUT} ≤ -15V)	V
Input Voltage Differential (Output Shorted to Ground)	35	V
Operating Junction Temperature	150	°C
Storage Temperature Range	-65 to 150	°C
Lead Temperature (Soldering 10 seconds)	300	°C

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

THERMAL DATA

Parameter	Value	Units
K Package TO-3 3-Pin Metal Can		
Thermal Resistance-Junction to Case, θ_{JC}	3	°C/W
Thermal Resistance-Junction to Ambient, θ_{JA}	35	°C/W
T Package TO-39 3-Pin Metal Can		
Thermal Resistance-Junction to Case, θ _{JC}	15	°C/W
Thermal Resistance-Junction to Ambient, θ_{JA}	120	°C/W
G Package TO-257 3-Pin Hermetic		
Thermal Resistance-Junction to Case, θ_{JC}	3.5	°C/W
Thermal Resistance-Junction to Ambient, θ_{JA}	42	°C/W
IG Package TO-257 3-Pin Hermetic (Isolated)		
Thermal Resistance-Junction to Case, θ _{JC}	4	°C/W
Thermal Resistance-Junction to Ambient, θ_{JA}	42	°C/W
L Package Leadless Chip Carrier 20-Pin Ceramic		
Thermal Resistance-Junction to Case, θ_{JC}	35	°C/W
Thermal Resistance-Junction to Ambient, θ_{JA}	120	°C/W

Notes:

^{1:} Junction Temperature Calculation: $T_J = T_A + (P_D \ x \ \theta_{JA})$.

^{2:} The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.



CHARACTERISTIC CURVES

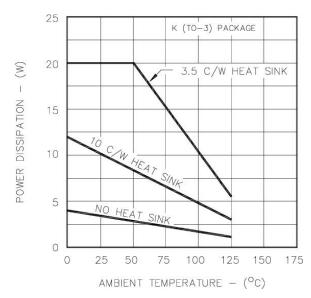


Figure 1 – Maximum Average Power Dissipation

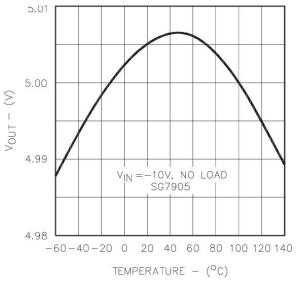


Figure 3 - Temperature Coefficient

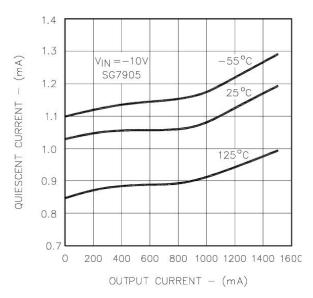


Figure 2 - Quiescent Current vs. Load

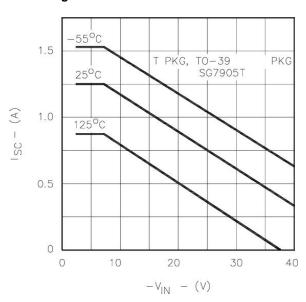


Figure 4 - Short-circuit Current vs. V_{IN}



CHARACTERISTIC CURVES (continued)

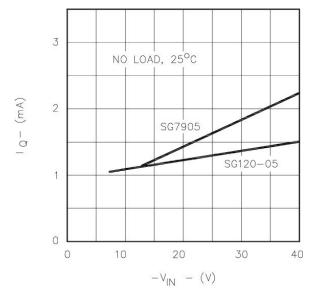


Figure 5 - Quiescent Current vs. V_{IN}

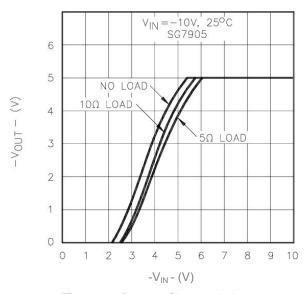


Figure 7 - Dropout Characteristics

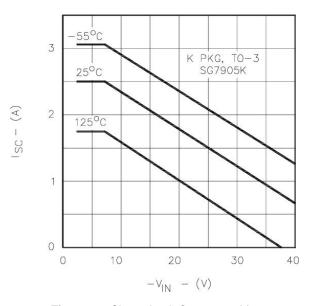


Figure 6 - Short-circuit Current vs. V_{IN}

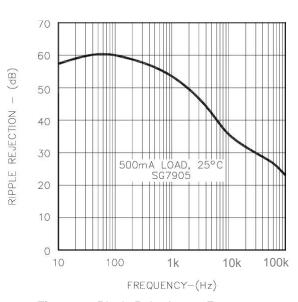


Figure 8 – Ripple Rejection vs. Frequency



APPLICATION INFORMATION

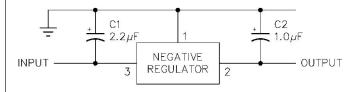


Figure 9 - Fixed Output Regulator

Note: 1. C1 is required only if regulator is separated from rectifier filter.

- Both C1 and C2 should be low E.S.R. types such as solid tantalum. If aluminum electrolytic capacitors are used, at least 10 times values shown should be selected.
- If large output capacities are used, the regulators must be protected from momentary input shorts. A high current diode is indicated from output to input.

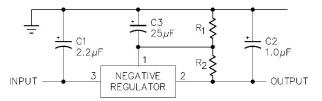


Figure 10 - Circuit for Increasing Output Voltage

Note: C3 optional for improved transient response and ripple rejection.

$$V_{OUT} = V \left(REGULATOR \right) \frac{R_1 + R_2}{R_1}$$

$$R_2 = \frac{V \left(REG \right)}{15mA}$$

RECOMMENDED OPERATING CONDITIONS

Parameter	SG7	9xx / 79x	κA	Units
Parameter		Тур	Max	Ullits
Operating Junction Temperature Range (Note 2)	-55		150	°C

Note 2: Range over which the device is functional.



ELECTRICAL CHARACTERISTICS

Unless otherwise specified, these specifications apply over the operating ambient temperatures for SG7905A / SG7905 with $-55^{\circ}C \leq T_{A} \leq 125^{\circ}C, \ V_{IN} = -10V, \ I_{O} = 500mA \ for the \ K, \ G, \ and \ I_{O} - Power Packages, \ I_{O} = 100mA \ for the \ T \ and \ L \ packages, \ C_{IN} = 2\mu F, \ and \ C_{OUT} = 1\mu F. \ Low \ duty \ cycle \ pulse \ testing \ techniques \ are \ used \ which \ maintains \ junction \ and \ case \ temperatures \ equal \ to \ the \ ambient \ temperature.$

		SG7905A			SG7905			11-24-
Parameter	Test Conditions	Min	Тур	Max	Min	Тур	Max	Units
Output Voltage	$T_J = 25^{\circ}C$	-4.95	-5.00	-5.05	-4.80	-5.00	-5.20	V
Line Develotion (Note 4)	V_{IN} = -7.5V to -25V, T_J = 25°C		5	25		3	50	mV
Line Regulation (Note 1)	V_{IN} = -8V to -12V, T_{J} = 25°C		3	12		1	25	mV
	Power Pkgs: I _O = 5mA to 1.5A, T _J = 25°C		15	75		15	100	mV
Load Regulation (Note 1)	I _O = 250mA to 750mA, T _J = 25°C		15	25		15	25	mV
	T – Pkg: I_0 = 5mA to 500mA, T_J = 250°C		5	30		5	100	mV
Total Output Voltage	V_{IN} = -8V to -20V Power Pkgs: I_O = 5mA to 1.0A, P \leq 20W	-4.85	-5.00	-5.15	-4.70	-5.00	-5.30	V
Tolerance	V_{IN} = -8V to -20V T - Pkg: I_O = 5mA to 500mA, P \leq 20W	-4.85	-5.00	-5.15	-4.70	-5.00	-5.30	V
Ovices and Oversent	Over Temperature Range			2.5			2.5	mA
Quiescent Current	T _J = 25°C			2.0			2.0	mA
	With Line: V _{IN} = -8V to -25V			1.3			1.3	mA
Quiescent Current Change	With Load: I _O = 5mA to 1.0A (Power Pkgs.)			0.5			0.5	mA
	I _O = 5mA to 500mA (T)			0.5			0.5	mA
Dropout Voltage	ΔV_{O} = 100mV, T _J = 25°C Power Pkgs: I _O = 1.0A, T-Pkg: I _O = 500mA		1.1	2.3		1.1	2.3	V
Dook Output Current	Power Pkgs: T _J = 25°C	1.5		3.3	1.5		3.3	Α
Peak Output Current	T – Pkg: T _J = 25°C	0.5		1.4	0.5		1.4	Α
Ob and Oliver it Our	Power Pkgs: V _{IN} = -35V, T _J = 25°C			1.2			1.2	Α
Short Circuit Current	T – Pkg: V _{IN} = -35V, T _J = 25°C			0.6			0.6	Α
Ripple Rejection	$\Delta V_{IN} = 10V$, f = 120Hz, $T_J = 25$ °C	54			54			dB
Output Noise Voltage (ms)	f = 10Hz to 100kHz (Note 2)		25	80		25	80	μV/V
Long Term Stability	1000 hours @ T _J = 125°C		20			20		mV
Thermal Shutdown	I _O = 5mA		175			175		°C

Notes 1: All regulation tests are made at constant junction temperature with low duty cycle testing.

^{2:} This test is guaranteed but is not tested in production.



ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise specified, these specifications apply over the operating ambient temperatures for SG7912A / SG7912 with -55°C \leq $T_A \leq$ 125°C, V_{IN} = -19V, I_O = 500mA for the K, G, and IG - Power Packages, I_O = 100mA for the T and L packages, C_{IN} = 2 μF , and C_{OUT} = 1 μF . Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

		SG7912A			SG7912			Units
Parameter	Test Conditions	Min	Тур	Max	Min	Тур	Max	Units
Output Voltage	T _J = 25°C	-11.8	-12.0	-12.2	-11.5	-12.0	-12.5	V
Line Description (Note 4)	V _{IN} = -14.5V to -30V, T _J = 25°C		4	60		10	120	mV
Line Regulation (Note 1)	V _{IN} = -16V to -22V, T _J = 25°C		3	30		3	60	mV
	Power Pkgs: I _O = 5mA to 1.5A, T _J = 25°C		20	90		12	120	mV
Load Regulation (Note 1)	$I_{\rm O}$ = 250mA to 750mA, $T_{\rm J}$ = 25°C		10	40		10	60	mV
	T – Pkg: I_0 = 5mA to 500mA, T_J = 25°C		10	40		10	240	mV
Total Output Voltage	V_{IN} = -14.5V to -27V Power Pkgs: I_O = 5mA to 1.0A, P \leq 20W	-11.7	-12.0	-12.3	-11.4	-12.0	-12.6	V
Tolerance	V_{IN} = -14.5V to -27V T - Pkg: I_0 = 5mA to 500mA, P \leq 2W	-11.7	-12.0	-12.3	-11.4	-12.0	-12.6	V
Outroped Comment	Over Temperature Range			4			4	mA
Quiescent Current	T _J = 25°C			3			3	mA
	With Line: V _{IN} = -14.5V to -30V			1.0			1.0	mA
Quiescent Current Change	With Load: I _O = 5mA to 1.0A (Power Pkgs.)			0.5			0.5	mA
	I _O = 5mA to 500mA (T)			0.5			0.5	mA
Dropout Voltage	$\Delta V_0 = 100 \text{mV}, \text{ TJ} = 25^{\circ}\text{C}$ Power Pkgs: $I_0 = 1.0 \text{A}, \text{ T} - \text{Pkg}$: $I_0 = 500 \text{mA}$		1.1	2.3		1.1	2.3	V
Dools Outrout Commant	Power Pkgs: T _J = 25°C	1.5		3.3	1.5		3.3	Α
Peak Output Current	$T - Pkg: T_J = 25^{\circ}C$	0.5		1.4	0.5		1.4	Α
Ob and Oliver it Ourseast	Power Pkgs: V _{IN} = -35V, T _J = 25°C			1.2			0.2	Α
Short Circuit Current	T – Pkg: V _{IN} = -35V, T _J = 25°C			0.6			0.6	Α
Ripple Rejection	$\Delta V_{IN} = 10V$, f = 120Hz, $T_J = 25$ °C	54			54			dB
Output Noise Voltage (ms)	f = 10Hz to 100kHz (note 2)		25	80		25	80	μV/V
Long Term Stability	1000 hours @ T _J = 125°C		60			60		mV
Thermal Shutdown	I _O = 5mA		175			175		°C

Notes 1: All regulation tests are made at constant junction temperature with low duty cycle testing.

^{2:} This test is guaranteed but is not tested in production.



ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise specified, these specifications apply over the operating ambient temperatures for SG7915A / SG7915 with $-55^{\circ}\text{C} \leq T_{A} \leq 125^{\circ}\text{C}$, $V_{IN} = -23V$, $I_{O} = 500\text{mA}$ for the K, G, and IG - Power Packages, $I_{O} = 100\text{mA}$ for the T and L packages, $C_{IN} = 2\mu\text{F}$, and $C_{OUT} = 1\mu\text{F}$. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

Donomoton	Toot Conditions	SG7915A			SG7915			Units
Parameter	Test Conditions	Min	Тур	Max	Min	Тур	Max	Units
Output Voltage	T _J = 25°C	-14.8	-15.0	-15.2	-14.4	-15.0	-15.6	V
Line Degulation (Note 1)	V _{IN} = -17.5V to -30V, T _J = 25°C		5	75		11	150	mV
Line Regulation (Note 1)	V _{IN} = -20V to -25V, T _J = 25°C		3	40		3	75	mV
	Power Pkgs: I_0 = 5mA to 1.5A, T_J = 25°C		30	100		12	150	mV
Load Regulation (Note 1)	I_0 = 250mA to 750mA, T_J = 25°C		4	50		4	75	mV
	$T - Pkg: I_O = 5mA \text{ to } 500mA, T_J = 25^{\circ}C$		10	50		10	240	mV
Total Output Voltage	V_{IN} = -18.5V to -30V Power Pkgs: I_{O} = 5mA to 1.0A, P \leq 20W	-14.6	-15.0	-15.4	-14.25	-15.00	-15.75	V
Tolerance	V_{IN} = -18.5V to -30V T - Pkg: I_0 = 5mA to 500mA, P \leq 2W	-14.6	-15.0	-15.4	-14.25	-15.00	-15.75	V
Quiescent Current	Over Temperature Range			4			4	mA
Quiescent Current	T _J = 25°C			3			3	mA
	With Line: $V_{IN} = -18.5V$ to $-30V$			1.0			1.0	mA
Quiescent Current Change	With Load: I _O = 5mA to 1.0A (Power Pkgs)			0.5			0.5	mA
	I _O = 5mA to 500mA (T)			0.5			0.5	mA
Dropout Voltage	ΔV_{O} = 100mV, T _J = 25°C Power Pkgs: I _O = 1.0A, T – Pkg: I _O = 500mA		1.1	2.3		1.1	2.3	٧
Peak Output Current	Power Pkgs: T _J = 25°C	1.5		3.3	1.5		3.3	Α
r eak Output Gurrent	T – Pkg: T _J = 25°C	0.5		1.4	0.5		1.4	Α
Chart Cinavit Command	Power Pkgs: V _{IN} = -35V, T _J = 25°C			1.2			1.2	Α
Short Circuit Current	$T - Pkg: V_{IN} = -35V, T_J = 25^{\circ}C$			0.6			0.6	Α
Ripple Rejection	$\Delta V_{IN} = 10V$, f = 120Hz, $T_J = 25$ °C	54			54			dB
Output Noise Voltage (ms)	f = 10Hz to 100kHz (note 2)		25	80		25	80	μV/V
Long Term Stability	1000 hours @ T _J = 125°C	_	60			60		mV
Thermal Shutdown	I _O = 5mA		175			175		°C

Notes 1: All regulation tests are made at constant junction temperature with low duty cycle testing.

^{2:} This test is guaranteed but is not tested in production.



CONNECTION DIAGRAMS & ORDERING INFORMATION (See Notes Below)

Package	Part No.	Ambient Temperature Range	Connection Diagram
	SG79xxAK-883B	-55°C to 125°C	
	SG7905AK-DESC	-55°C to 125°C	GND
	SG7912AK-DESC	-55°C to 125°C	
	SG7915AK-DESC	-55°C to 125°C	
3-Terminal TO-3 Metal Can	SG79xxAK	-55°C to 125°C	$(\bigcirc (\bigcirc (\bigcirc)))$
K – Package	SG79xxK-883B	-55°C to 125°C	\bigcirc \bigcirc \bigcirc \bigcirc \bigcirc
3	SG7905K-JAN	-55°C to 125°C	
	SG7912K-JAN	-55°C to 125°C	V _{OUT}
	SG7915K-JAN	-55°C to 125°C	Case is V _{IN}
	SG79xxK	-55°C to 125°C	
	SG79xxAT-883B	-55°C to 125°C	
	SG7905AT-DESC	-55°C to 125°C	V _{out}
	SG7912AT-DESC	-55°C to 125°C	
	SG7915AT-DESC	-55°C to 125°C	(2)
3-Pin TO-39 Metal Can	SG79xxAT	-55°C to 125°C	
T – Package	SG79xxT-883B	-55°C to 125°C	V _{IN} (3) (1) GND
_	SG7905T-JAN	-55°C to 125°C	
	SG7912T-JAN	-55°C to 125°C	
	SG7915T-JAN	-55°C to 125°C	Case is V _{IN}
	SG79xxT	-55°C to 125°C	Odde 13 VIN
	SG79xxAIG-883B	-55°C to 125°C	
	SG7905AIG-DESC	-55°C to 125°C	
3-Pin Hermetic TO-257	SG7912AIG-DESC	-55°C to 125°C	Vout
IG – Package (Isolated)	SG7915AIG-DESC	-55°C to 125°C	V _{IN}
IG – Package (Isolateu)	SG79xxAIG	-55°C to 125°C	GROUND
	SG79xxIG-883B	-55°C to 125°C	
	SG79xxIG	-55°C to 125°C	
	SG79xxL-883B	-55°C to 125°C	Ŭ
	SG79xxL	-55°C to 125°C	3 2 1 20 19
	SG7905AL-DESC	-55°C to 125°C	V _o 4 18 (N.C.
20-Pin Ceramic Leadless Chip	SG7912AL-DESC	-55°C to 125°C	V _o p ⁵ 17 GROUND
Carrier	SG7912AL-DESC	-55°C to 125°C	N.C. 06 16 N.C.
L – Package			V _o SENSE) ⁷ 15 (GROUND
3.3			N.C. 08 14 (N.C.
			9 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0
	SG79xxAG-883B	-55°C to 125°C	000 110100 0 0 0
	SG7905AG-DESC	-55°C to 125°C	
	SG7912AG-DESC	-55°C to 125°C	V _{out}
3-Pin Hermetic TO-257	SG7915AG-DESC	-55°C to 125°C	V _{IN} GROUND
G – Package (Case is V _{IN})	SG79xxAG	-55°C to 125°C	
	SG79xxG-883B	-55°C to 125°C	Case is V _{IN}
	SG79xxG	-55°C to 125°C	

Notes

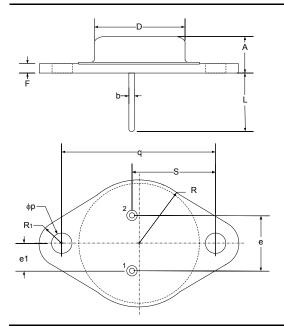
- 1: Contact factory for JAN and DESC product availability.
- 2: All parts are viewed from the top.

 3: "xx" to be replaced by output voltage of specific fixed regulator.
- 4: Some products will be available in hermetic flat pack (F). Consult factory for price and availability. 5: Both inputs and outputs must be externally connected together at the device terminals.
- 6: For normal operation, the $V_{\rm O}$ SENSE pin must be externally connected to the load.



PACKAGE OUTLINE DIMENSIONS

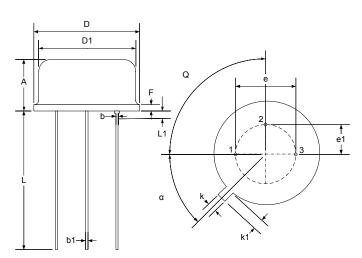
Controlling dimensions are in inches, metric equivalents are shown for general information.



Dim	MILLIMETER		INCHES		
Dilli	MIN	MAX	MIN	MAX	
Α	6.86	7.62	0.270	0.300	
q	29.90	30.40	1.177	1.197	
b	0.97	1.09	0.038	0.043	
D	19.43	19.68	0.765	0.775	
S	16.64	17.14	0.655	0.675	
е	10.67	11.18	0.420	0.440	
e1	5.21	5.72	0.205	0.225	
F	1.52	2.03	0.060	0.080	
фр	3.84	4.09	0.151	0.161	
L	10.79	12.19	0.425	0.480	
R1	3.33	4.78	0.131	0.188	
R	12.57	13.34	0.495	0.525	

Note: Dimensions do not include protrusions; these shall not exceed 0.155 mm (0.006") on any side. Lead dimension shall not include solder coverage.

Figure 11 · K 3-Pin Metal Can TO-3



Dim	MILLIM	ETERS	INCHES		
Dilli	MIN	MAX	MIN	MAX	
Α	4.19	4.70	0.165	0.185	
b	0.41	0.48	0.016	0.019	
b1	0.41	0.53	0.016	0.021	
D	8.89	9.40	0.350	0.370	
D1	8.13	8.51	0.320	0.335	
е	5.08 BSC		0.200	BSC	
e1	2.54	Тур	0.100) Тур	
F	-	1.02	-	0.040	
k	0.71	0.86	0.028	0.034	
k1	0.74	1.14	0.029	0.045	
L	12.70	14.48	0.500	0.570	
L1	-	1.27	-	0.050	
Q	90° Typ		90° Typ		
α	45°	Тур	45° Typ		

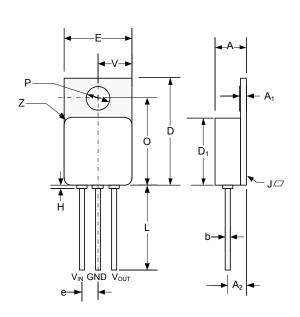
^{*} Lead Coplanarity

Note: Dimensions do not include protrusions; these shall not exceed 0.155 mm (0.006") on any side. Lead dimension shall not include solder coverage.

Figure 12 · T 3-Pin Metal Can TO-39



PACKAGE OUTLINE DIMENSIONS (continued)

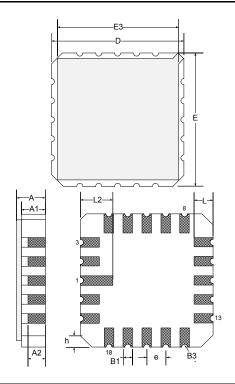


Dim	MILLIME	ETERS	INCHES		
Dilli	MIN	MAX	MIN	MAX	
Α	4.70	5.21	0.185	0.205	
A1	0.89	1.14	0.035	0.045	
A2	2.92	3.18	0.115	0.125	
b	0.71	0.081	0.027	0.032	
D	16.38	16.76	0.645	0.660	
D1*	10.41	10.92	0.410	0.430	
е	2.54 l	BSC	0.100) BSC	
E*	10.41	10.67	0.410	0.420	
Н		0.50		0.020	
L	12.70		0.500		
0	13.39	13.64	0.527	0.537	
Р	3.56	3.81	0.140	0.150	
J		0.10		0.004	
V	5.13	5.38	0.202	0.212	
Ζ	1.40	Тур	0.05	5 Тур	

^{*}Excludes Weld Fillet Around Lid.

Note: Dimensions do not include protrusions; these shall not exceed 0.155 mm (0.006") on any side. Lead dimension shall not include solder coverage.

Figure 13 - G/IG 3-Pin Hermetic TO-257



Dim	MILLIM	ETERS	INC	HES
Dim	MIN	MAX	MIN	MAX
D, E	8.64	9.14	0.340	0.360
E3	-	8.128	-	0.320
е	1.270	BSC	0.050) BSC
B1	0.635	0.635 Typ		5 Тур
L	1.02	1.52	0.040	0.060
Α	1.626	2.286	0.064	0.090
h	1.016 Typ		0.04	0 Тур
A1	1.372	1.68	0.054	0.066
A2	-	1.168	-	0.046
L2	1.91	2.41	0.075	0.95
В3	0.20)3R	0.008R	

Note: All exposed metalized area shall be gold plated 60 μ -inch minimum thickness over nickel plated unless specified in purchase order. Lead dimension shall not include solder coverage.

Figure 14 · L 20-Pin Ceramic Leadless Chip Carrier



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